

What is claimed:

- 5 [0041] 1. A printed circuit board (PCB), comprising:
a mounting area for attaching one or more heat producing devices; and
a coolant circulation channel at least partially formed in a layer of the PCB, the
channel having a portion in a vicinity of the mounting area.
- [0042] 2. The PCB of claim 1, wherein the PCB is a multi-layer PCB, and
wherein a portion of the channel is formed by removal of portions of one or more layers
of the PCB.
- 10 [0043] 3. The PCB of claim 1, wherein the PCB is a multi-layer PCB, and
wherein a portion of the channel is formed by coinciding vias in located in adjacent
layers of the PCB.
- 15 [0044] 4. The PCB of claim 1, wherein the channel carries a coolant.
- [0045] 5. The PCB of claim 4, wherein the coolant is a gas.
- [0046] 6. The PCB of claim 4, wherein the coolant is a liquid.
- 20 [0047] 7. The PCB of claim 4, wherein a portion of the channel is formed by
a surface of a device attached to the mounting area, so as to provide direct contact
between the device and the coolant.

[0048] 8. The PCB of claim 7, wherein the device comprises a transistor die attached to a mounting flange, the mounting flange attached to the mounting area and comprising the surface forming the respective portion of the channel.

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[0049] 9. The PCB of claim 1, wherein the device comprises a transistor die attached to the mounting area.

[0050] 10. The PCB of claim 7, wherein the device comprises a transistor die attached to the mounting area, the transistor die comprising the surface forming the respective portion of the channel.

[0051] 11. The PCB of claim 1, comprising a plurality of device mounting areas for attaching heat producing devices, the channel having a portion in a vicinity of each mounting area.

[0052] 12. An assembly comprising a heat-generating device attached to a printed circuit board (PCB), and a thermal management system, the thermal management system comprising a coolant circulation channel at least partially formed in a layer of the PCB.

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[0053] 13. The assembly of claim 12, further comprising a heat sink, the channel including a portion in thermal contact with the heat sink.

[0054] ³
~~14.~~ The assembly of claim ¹~~12~~, further comprising a pump arranged for circulating a coolant through the channel.

5 [0055] ⁴
~~15.~~ The assembly of claim ¹~~12~~, wherein the PCB is a multi-layer PCB, and wherein a portion of the channel is formed by removal of portions of one or more layers of the PCB.

[0056] ⁵
~~16.~~ The assembly of claim ¹~~12~~, wherein the PCB is a multi-layer PCB, and wherein a portion of the channel is formed by coinciding vias located in adjacent layers of the PCB.

[0057] ⁶
~~17.~~ The assembly of claim ¹~~12~~, wherein the channel carries a gas coolant.

[0058] ⁷
~~18.~~ The assembly of claim ¹~~12~~, wherein the channel carries a liquid coolant.

[0059] ⁸
~~19.~~ The assembly of claim ¹~~12~~, wherein a portion of the channel is formed by a surface of the device, so as to provide direct contact between the device and a coolant carried in the channel.

[0060]

⁹
~~20~~The assembly of claim ⁸
~~10~~,

wherein the device comprises a transistor die attached to a mounting flange, the mounting flange attached to the PCB mounting area and comprising the surface forming the respective portion of the channel.

[0061]

¹⁰
~~21~~The assembly of claim ¹
~~12~~,

wherein the device comprises a transistor die attached to the PCB mounting area.

[0062]

¹¹
~~22~~The assembly of claim ⁸
~~10~~,

wherein the device comprises a transistor die attached to the PCB mounting area, the transistor die comprising the surface forming the respective portion of the channel.

[0063]

¹²
~~23~~The assembly of claim ¹
~~12~~,

the PCB comprising a plurality of device mounting areas for attaching heat producing devices, the cooling channel having a portion in a vicinity of each mounting area.